Super Flux Infrared LED

Features:

* High Power LED Lamp with High Flux Output for High Current Operation
* Low Thermal Resistance
* Low Profile
* Tube Package for Automatic Insertion Equipment

Chip Materials:

* Dice Material : GaAlAs/GaAs
* Lens Color : Water Clear

Absolute Maximum Rating : (Ta = 25°C)

Symbol	Parameter	Max.	Unit
P_{AD}	Power Dissipation Per Chip	200	mW
V_R	Reverse Voltage Per Chip	5	V
I_F	Forward Current Per Chip	100	mA
I_{PF}	Peak forward current Per Chip (F=1KHZ,duty=0.1)	400	mA
Topt	Operating Temperature Range	-35°C to 85°C	
Tstg	Storage Temperature Range	-35°C to 85°C	
Lead Soldering Temperature { 1.6mm(0.063 inch) From Body } 260°C ± 5°C for 5 Seconds			

Electro-Optical Characteristics : (Ta = 25°C)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
V_F	Forward Voltage	I_F = 20mA I_F = 150mA		1.6 1.8	1.9 2.4	V
I_R	Reverse Current	V_R = 5V			10	μA
λP	Peak Emission Wavelength	I_F = 20mA		850		nm
2θ1/2	Half Intensity Angle	I_F = 20mA		note1		deg
I_E	Radiant Intensity	I_F = 20mA I_F=150mA		30 180		mw/sr

Note 1: Available : 30, 40, 50, 90 deg.

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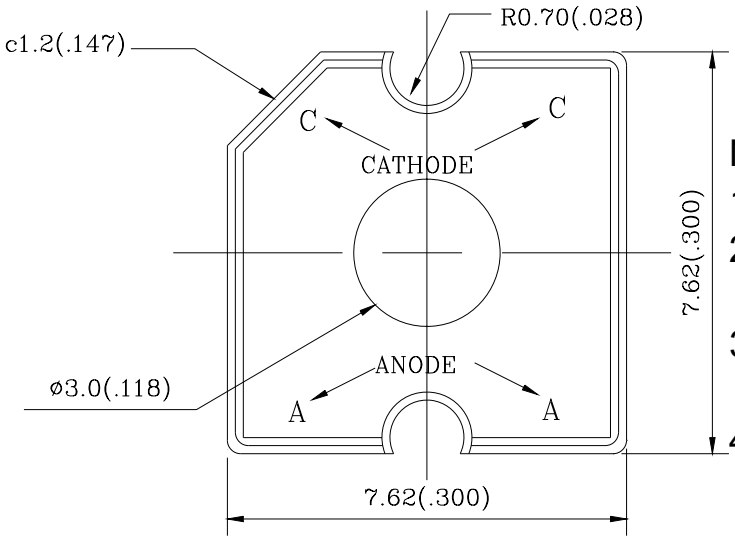
Package Dimensions



Note:
1.All Dimensions are in millimeters.
2.Tolerance is ±0.25mm(0.010 ")
Unless otherwise specified.
3.Protruded resin under flange
is 1.5mm(0.059 ") max.
4.Lead spacing is measured where
the leads emerge from the package.